



Material Content Data Sheet



Sales Product Name				IPD050N03L G		Issued		20. July 2018	
MA#				MA000638988					
Package				PG-TO252-3-311		Weight*		317.08 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.415	0.45	0.45	4463	4463	
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		136		
	non noble metal	iron	7439-89-6	0.143	0.05		452		
	non noble metal	copper	7440-50-8	143.098	45.12	45.18	451293	451881	
	non noble metal	aluminium	7429-90-5	2.190	0.69	0.69	6905	6905	
wire	non noble metal	aluminium	7429-90-5	2.190	0.69	0.69	6905	6905	
encapsulation	organic material	carbon black	1333-86-4	0.320	0.10		1010		
	plastics	epoxy resin	-	19.336	6.10		60980		
	inorganic material	silicondioxide	60676-86-0	125.945	39.72	45.92	397197	459187	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11795	11795	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	273	274	
solder	non noble metal	tin	7440-31-5	0.031	0.01		99		
	noble metal	silver	7440-22-4	0.039	0.01		123		
	non noble metal	lead	7439-92-1	1.494	0.47	0.49	4713	4935	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		61		
	non noble metal	copper	7440-50-8	19.177	6.05	6.06	60481	60560	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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